

## APPENDIX

## Changes to Claims:

The following is a marked-up version of the amended claims:

1. (Amended) A method of manufacturing a semiconductor device in which a semiconductor chip on which electrodes are formed, and a substrate on which an interconnect pattern is formed and which is covered by a protective layer except a region in said interconnect pattern of electrical connection with said electrodes, are connected by an adhesive, said method comprising:

a first step of providing said adhesive on said substrate from a region of mounting of said semiconductor chip to said protective layer, ~~between said interconnect pattern and said electrodes~~ said adhesive, said protective layer and said interconnect pattern overlapping with one another outside of said region of mounting of said semiconductor chip; and

a second step of adhering said substrate to said semiconductor chip by means of said adhesive to electrically connect said interconnect pattern with said electrodes.

21. (Amended) A semiconductor device comprising:

a semiconductor chip having electrodes; a substrate on which an interconnect pattern is formed; a protective layer provided on said substrate excluding a region of said interconnect pattern of electrical connection with said electrodes of said semiconductor chip; and an adhesive;

wherein said adhesive is provided on said substrate from a region of mounting of said semiconductor chip to said protective layer, said adhesive, said protective layer and said interconnect pattern overlapping with one another outside of said region of mounting of said semiconductor; and

wherein said electrodes of said semiconductor chip are electrically connected with said interconnect pattern.

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